



4.40-5.00 GHz 4-Watt Internally Matched Power FET

FEATURES

- 4.40–5.00GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +36.5 dBm Output Power at 1dB Compression
- 11.5 dB Power Gain at 1dB Compression
- 37% Power Added Efficiency
- -46 dBc IM3 at PO = 25.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}





Caution! ESD sensitive device.

ELECTRICAL CHARACTERISTICS ($T_a = 25^{\circ}C$)

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 4.40-5.00GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$	35.5	36.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 4.40-5.00GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$	10.5	11.5		dB
ΔG	Gain Flatness $f = 4.40-5.00GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression V_{DS} = 10 V, I_{DSQ} ≈ 1100mA f = 4.40-5.00GHz		37		%
Id_{1dB}	Drain Current at 1dB Compression f = 4.40-5.00GHz		1200	1500	mA
IM3	Output 3rd Order Intermodulation Distortion Δf = 10 MHz 2-Tone Test; Pout = 25.5 dBm S.C.L ² V_{DS} = 10 V, I_{DSQ} ≈ 65% IDSS f = 5.00GHz	-43	-46		dBc
I _{DSS}	Saturated Drain Current V _{DS} = 3 V, V _{GS} = 0 V		2000	2500	mA
V _P	Pinch-off Voltage V _{DS} = 3 V, I _{DS} = 20 mA		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		5.5	6.0	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

- 2. S.C.L. = Single Carrier Level.
- 3. Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS	SYMBOLS PARAMETERS		CONTINUOUS ²	
Vds	Drain-Source Voltage	15V	10V	
Vgs	Vgs Gate-Source Voltage		-4V	
Igf Forward Gate Current		48mA	14mA	
Igr Reverse Gate Current		-9.6mA	-2.4mA	
Pin	Input Power	36dBm	@ 3dB Compression	
Tch	Channel Temperature	175C	175C	
Tstg	Tstg Storage Temperature		-65C to +175C	
Pt	Pt Total Power Dissipation		25W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

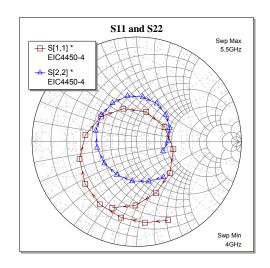
2. Exceeding any of the above ratings may reduce MTTF below design goals.

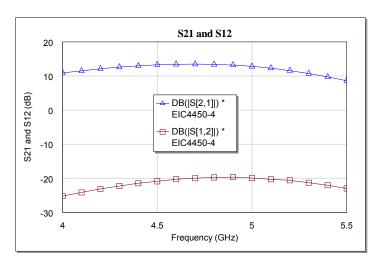


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PERFORMANCE DATA

Typical S-Parameters (T= 25°C, 50Ω system, de-embedded to edge of package) V_{DS} = 10 V, I_{DSQ} ≈ 1100mA





FREQ	S11		S21		S12		S21 S12		S	22
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG		
4.00	0.808	-68.190	3.508	99.990	0.055	37.090	0.424	-52.880		
4.25	0.713	-110.590	4.141	59.190	0.074	-2.750	0.368	-108.070		
4.50	0.570	-163.190	4.620	13.810	0.090	-49.090	0.382	-171.490		
4.75	0.383	129.460	4.719	-34.020	0.102	-96.850	0.429	132.270		
5.00	0.301	28.000	4.375	-83.660	0.100	-145.990	0.431	82.100		
5.25	0.481	-56.790	3.625	-132.810	0.090	165.590	0.364	33.460		
5.50	0.671	-110.260	2.699	-177.940	0.071	122.650	0.268	-19.720		
5.75	0.795	-149.080	1.929	141.910	0.053	84.390	0.240	-76.080		
6.00	0.869	-179.020	1.365	106.080	0.040	51.160	0.290	-122.110		
6.25	0.909	156.420	0.965	72.960	0.028	27.210	0.380	-155.490		
6.50	0.933	135.760	0.681	42.570	0.020	0.750	0.488	178.060		

Revised October 2007

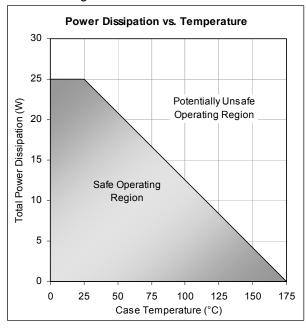
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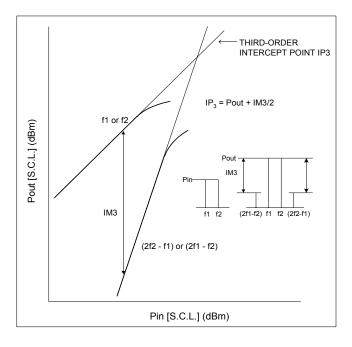




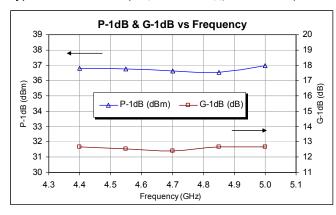
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Power De-rating Curve and IM3 Definition

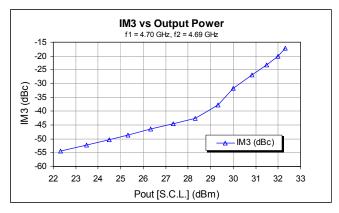




Typical Power Data ($V_{DS} = 10 \text{ V}$, $I_{DSQ} = 1100 \text{ mA}$)



Typical IM3 Data ($V_{DS} = 10 \text{ V}$, $I_{DSQ} \approx 65\% \text{ IDSS}$)





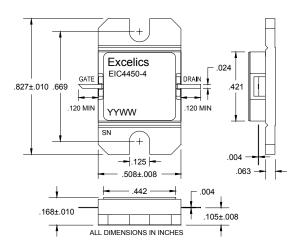


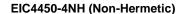
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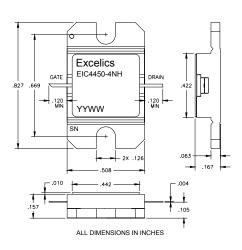
PACKAGES OUTLINE

Dimensions in inches, Tolerance + .005 unless otherwise specified

EIC4450-4 (Hermetic)









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ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	$IM_3 (min)^2$
EIC4450-4	Hermetic	Industrial	4.40-5.00GHz	35.5	-43
EIC4450-4NH	Non-Hermetic	Industrial	4.40-5.00GHz	35.5	-43

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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